APPLICA	BLE STAN	IDARD									
	Operating temperature ra	nge	-55°C to 85°C	D		erature		-1	10℃ TO 50℃(packed	cond	ition)
RATING	Voltage		30V AC/DC			ating or dity ran	storage ge	Relative humidity 90%MAX(not dew			
	Current		0.20A		Appli	cable ca	able		t=0.2±0.02mm, gold p	lating	J
			SPEC	IFICA	TIOI	NS					
IT	EM		TEST METHOD				RE	QUII	REMENTS	QT	АТ
CONSTR	UCTION	•				•					
General exar	mination	Visually a	and by measuring instrumen	nt.		According to drawing.				×	×
Marking		Confirme	d visually.			(note 1,2)				×	×
ELECTRI	CAL CHA	RACTE	RISTICS								
Voltage proo	f	90V AC for 1 min.			No flashover or breakdown.				×	×	
Insulation resistance		100V DC.			50MΩ MIN.				×	×	
Contact resistance		20mV AC MAX, 1mA.			300mΩ MAX. Including FPC, FFC bulk resistance (L=8mm)				×	×	
MECHAN	IICAL CH	ARACTE	RISTICS				-				
Vibration		Frequency 10 to 55 Hz, half amplitude 0.75 mm,			٦,	① No	electrical d	isco	ntinuity of 1us	×	_
		for 10 cycles in 3 axial directions.				① No electrical discontinuity of 1μs. ② Contact resistance: 300mΩ MAX.					1
Shock		981 m/s ² , duration of pulse 6 ms at 3 times in 3 both axial directions.							and loose parts.	×	
Mechanical o	peration	10 times	10 times insertions and extractions.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. 				×	-
FPC retentio	n force		Measured by applicable FPC. (thickness of FPC shall be t=0.20mm at initial ondition)			Direction of insertion: (0.14 × n)+1N MIN(<i>note 3</i>) (n: Number of contacts)			×	-	
ENVIRO	NMENTAL	,	ACTERISTICS	at initial ona	11.011)	(11. 1401	TIDET OF COL	itact	3)		
						_			: 300mΩ MAX.	×	T -
Corrosion salt mist		Exposed at 35±2°C, 5% salt water spray for 96h.			② No damage, crack and loose parts.③ No evidence of corrosion which affects connector's operation.						
Rapid change of temperature		Temperature-55 \rightarrow +15To+35 \rightarrow +85 \rightarrow +15To+35°C Time 30 \rightarrow 2 To 3 \rightarrow 30 \rightarrow 2 To 3 min			① Contact resistance: 300mΩ MAX. ② Insulation resistance: 50MΩ MIN.				×	_	
Damp heat		Under 5 cycles. Exposed at 40±2°C,			No damage, crack and loose parts.				×	+-	
steady state	e)		umidity 90 to 95%, 96h.			_					
Damp heat,cyclic		Exposed at -10 to +65°C, relative humidity 90 to 96%, 10 cycles, total 240h.			 Contact resistance: 300mΩ MAX. Insulation resistance: 1MΩ MIN. (at high humidity) Insulation resistance: 50MΩ MIN. (at dry) No damage, crack and loose parts. 			×	_		
Dry heat		Exposed	Exposed at 85±2°C, 96h.			① Contact resistance: 300mΩ MAX.				×	1-
Cold			osed at -55±3°C, 96h.			② No damage, crack and loose parts.				×	-
Sulphur dioxide [JIS C 60068-2-42]		relative h	ed at 40±2°C, e humidity 80±5%, ppm for 96h.			 Contact resistance: 300mΩ MAX. No damage, crack and loose parts. 				×	
Hydrogen sulphide [JIS C 60068-2-43]		relative h	l at 40±2°C, numidity 80±5%, opm for 96h.			③ No evidence of corrosion which affects connector's operation.			×	_	
COUNT DESCRIPT			ON OF REVISIONS	OF REVISIONS DESIG			GNED CHECKED			DATE	
				<u> </u>			1.5				
REMARK					APPROVE					06. 07	
						CHECKEI		-+	YH. MICHIDA	16.0	
الانتاجة علمالا		ا د اداند	ied_refer to IEC 60512								06. 07
Unless otherwise specified,						DRAWN DRAWN		١	OTNIEL RINALDO 16. ELC-370587-00-0)6. 06
Note QT:Qualification Test AT:						RAWING NO.			FH58-**S-0. 2SHW		J
Π			ECHIOATION SHEET			NO.				^	4 /0
		OSE ELECTRIC CO., LTD. CODE			: NO.		(CL580		1/2	

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Solderability	Soldered at solder temperature 245±3°C, for immersion duration 3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95% of the surface being immersed.	×	_				
Resistance to soldering heat	 Reflow soldering: peak tmp. 250°C MAX. reflow tmp. over 230°C within 60 sec. Soldering irons: tmp. 350±10°C for 5±1 sec. 	No case-deformation and loose contacts. (note 4)	×	_				

(note1)

This connector is back flip lock type, and top/bottom both contact points are available.

(note2)

Do not close the actuator before inserting FPC even after the connector is mounted onto a PCB.

Closing the actuator without FPC could make the contact gap smaller, which increases the FPC insertion force.

(note3)

If pull-up or pull-down force is exepected to be applied to the FPC, stabilize the FPC into PCB or other fixed components.

(note4)

Blisters which may be generated on the housing do not affect product performance.

Note (Note QT:Qualification Test AT:Assurance Test X:Applicable Test			IG NO.	ELC-370587-00-00			
H	SPECIFICATION SHEET		PART NO. FH58-**S-0. 2SHW					
)	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	\triangle	2/2	